

IN THE SPECIFICATION:

Please amend paragraph [0049] as follows:

[0049] The substrate 12 includes a circuit side 62 (FIG. 5) and an opposing back side 64 (see FIG. 3), which in this embodiment comprises the card's back face 22. In FIG. 5, a longitudinal center line 94 of strip 44, and a longitudinal center line 96 of module 48 are shown for reference. A peripheral edge 72 (not shown) joins the circuit side 62 and the opposing back side 64 of the substrate 12. As illustrated in the exemplary substrate 12 of FIG. 5, the circuit side 62 has mounted therein semiconductor elements 16, as well as electrical components 74, such as resistors, capacitors, and inductors. A circuit is completed by connecting the semiconductor elements 16, electrical components 74 and external contacts 18 (see FIG. 3) with a pattern of conductors, e.g., wires, printed conductors, vias, and the like, not shown in the figures. Contacts (not shown) may also be provided to establish test circuits for example, typically on the circuit side 62 of the substrate. Methods and apparatus for forming, attaching and conductively interconnecting semiconductor elements 16, electrical components 74 and external contacts 18 are well known in the art. The circuit on the substrate 12 may be configured to perform a desired function, such as ~~as~~ as, for example, memory storage, sound production, video production, games, product identification, etc.

Please amend paragraph [0054] as follows:

[0054] Turning now to FIGS. 7 through 9, which show the first (lower) plate 84 of a representative molding apparatus 80 for forming a semiconductor card 10 from a substrate 12. The first plate 84 has an upper side 140 with an internal surface 160A, and a lower side or base 138. The first plate 84 includes a peripheral raised portion 108 to hold a module frame 46 at a first level 110. The outer edge 122 of peripheral raised portion 108 may be dimensionally smaller than the module 48. A depressed portion 112 laterally inside of the peripheral raised portion 108 is configured to accept a substrate 12 at lower level 114, with space for forming a plastic periphery about the substrate. The substrate is connected to the frame 46 by connecting segments 56. Portions 116 of the depressed portion 112 may be depressed further to

accommodate external contacts 18 protruding from the opposing back side 64 of the substrate 12. Laterally intermediate the peripheral raised portion 108 and the depressed portion 112 is a lower edge portion 118 of the lower plate 84. The lower edge portion 118 has an inner arcuate surface 120 for forming rounded corners 38 and rounded longitudinal edges 40, 42 on the semiconductor card 10. The lower edge portion 118 passes upward through the peripheral opening 54 of the module 48, and in some locations, its upper surface 124 generally abuts the upper plate 86 to form a flash free seam on the peripheral edge 36 of the semiconductor card 10. As shown, a plurality of slits 126 ~~are~~ is formed through the lower edge portion 118 and peripheral raised portion 108 for passage of connecting segments 56 of the module 48 therethrough. The numbers and locations of the plurality of slits 126 (and matching connecting segments 56) provide for downwardly motivated support of the substrate 12 in the depressed portion 112.